

High Efficiency, Synchronous Buck Charger for 1-3 cell Li-ion Battery with Power Path management

1 DESCRIPTION

The SC89133 is a highly integrated switch-mode buck charger for 1-3 cells Li-ion battery applications. It supports 4.2 ~ 24V input, up to 5A charging current and provide battery charge management functions including trickle charge, constant current charge, constant voltage charge, charge termination, auto recharge and charging status indication.

SC89133 also integrates NMOS driver and PMOS driver for Power path management, it is easy to support dynamic power management for charging and system power.

The SC89133 supports flexible charge current and input current option, and the user can program the current freely through external resistor for different applications.

The SC89133 supports input current limit, input over voltage and under voltage protections, internal cycle by cycle current limit, battery short circuit protection, and battery over voltage protection. It also offers charging safety timer and battery temperature protection to ensure safety under different abnormal conditions.

Besides, SC89133 keeps monitoring IC temperature and automatically decreases charging current to ensure IC working in normal temperature range.

The SC89133 is available in QFN-3.5*5.5 package.

3 APPLICATIONS

- Blue-tooth speaker charger
- Portable Media Players
- Notebook, Tablet
- POS machine

2 FEATURES

- Wide Input Voltage: 4.2V ~ 24V
- Integrated Low-Rdson Synchronous Buck Charger, Efficiency up to 97%
- Charging Management (Trickle Charge / Constant Current Charge / Constant Voltage Charge / Charge Termination/Auto-Recharge)
- Adjustable Input Current Limit and Charging Current
- Selectable Constant Voltage
 - 4.2V/8.4V/12.6V for 1 to 3 cells battery
- Power Path Management for System Power Selector
- Adjustable Charge Safety Timer
- NTC Supporting JEITA Standard for Battery temperature Protection
- Charging Status Indication
- Adjustable Input Over Voltage and Under Voltage Protection
- Battery Over Voltage Protection
- Battery Short Circuit Protection
- Charging Over Current and Under Current Protection
- Thermal Regulation and Shutdown
- QFN 3.5*5.5 footprint

4 DEVICE INFORMATION

Part Number	Package	Dimension
SC89133QDNR	24 pin QFN	3.5mm x 5.5mm

5 Typical Application Circuit

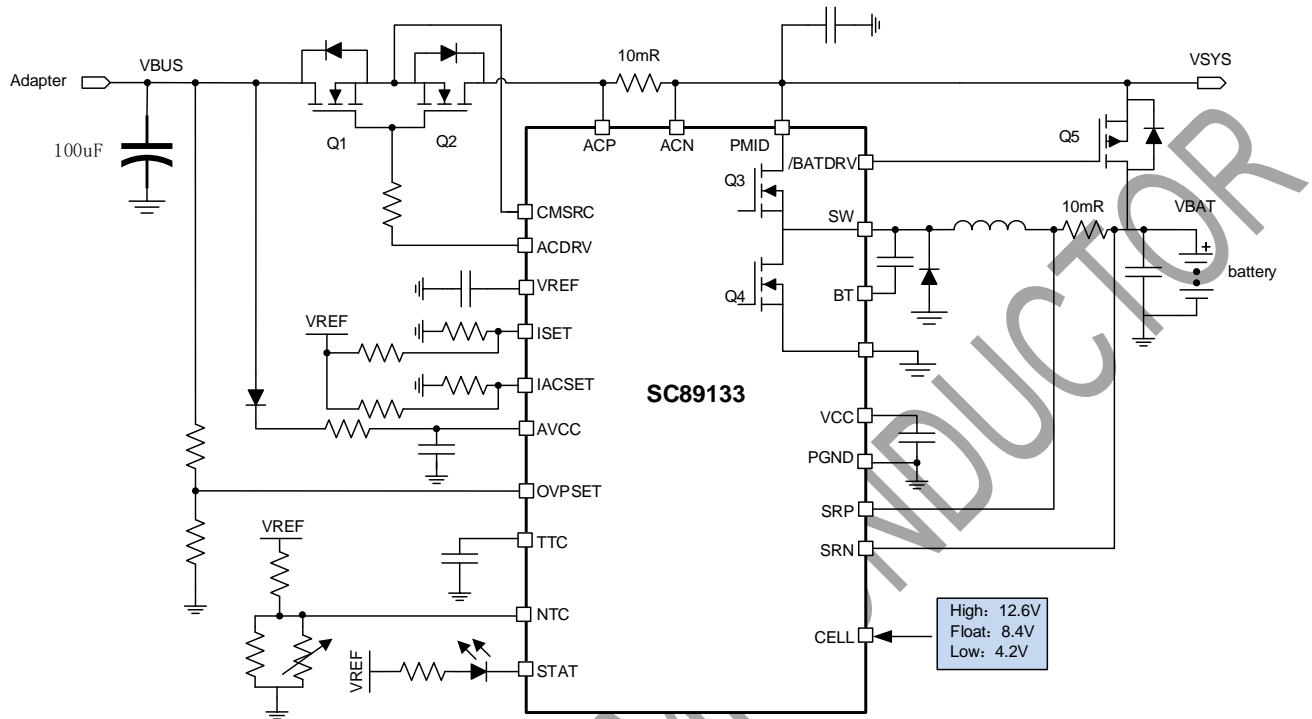


Figure 1. SC89133 with power path application

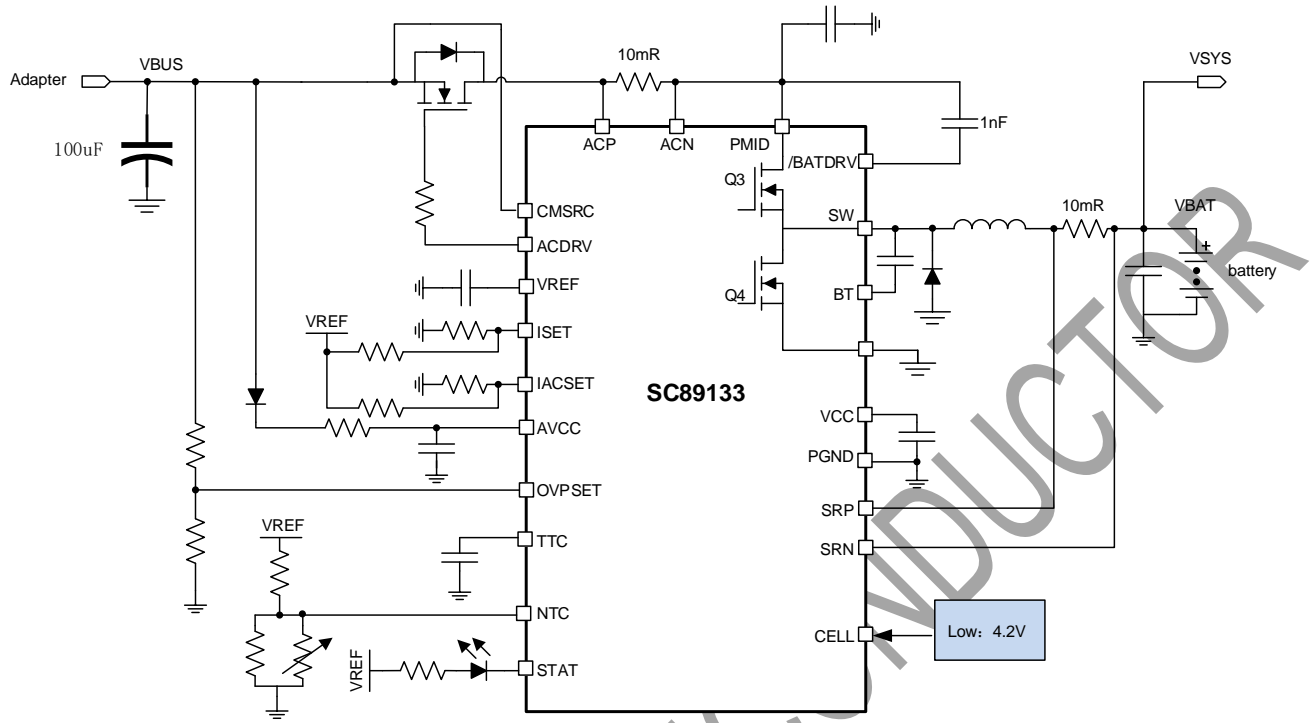
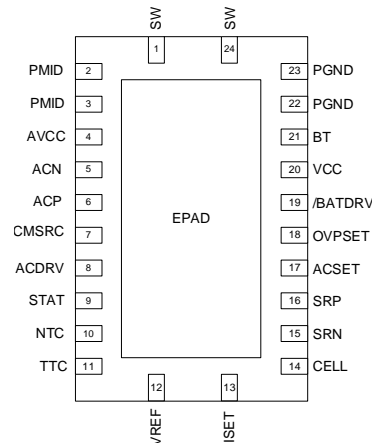


Figure 2. SC89133 without power path application for 1 cell

6 Terminal Configurations and Functions

QFN 3.5x5.5



I/O			DESCRIPTION
SC89133	NAME		
1, 24	SW	I/O	Switching node of the buck converter. Connect to external inductor.
2, 3	PMID	I	Input of buck charger to charge the battery cells. Connected to the drain of the reverse blocking MOSFET.
4	AVCC	I	IC power positive supply. Place a 1 μ F ceramic capacitor from AVCC to AGND and place it as close as possible to IC.
5	ACN	I	Adapter input current sense resistor negative input.
6	ACP	I	Adapter input current sense resistor positive input.
7	CMSRC	O	Connect to common source of ACFET and reverse blocking FET.
8	ACDRV	O	Blocking FET driver output. Connect to the gate of blocking FET.
9	STAT	O	Charge status indication. Open drain output. Connect it to pull-up,
10	NTC	I	Temperature sense pin. Connect to the Negative Temperature Coefficient (NTC) thermistor inside the battery cells to sense the battery cells temperature for protection. Short this pin to ground to disable this function.
11	TTC	I	Safety Timer and termination control. Low: disable both safety timer and charge termination High: only disable safety timer
12	VREF	O	3.3-V reference voltage output. Place a 1- μ F ceramic capacitor from VREF to AGND pin close to the IC.
13	ISET	I	Charging current setting pin.
14	CELL	I	Battery voltage select pin.
15	SRN	I	Charging current sense resistor negative input.
16	SRP	I	Charging current sense resistor positive input.
17	ACSET	I	Adapter input current limit setting pin.
18	OVPSET	I	Adapter input voltage setting pin. Connected with a resistor divider from VBUS to AGND to set charger working range.
19	/BATDRV	O	BATFET gate driver output.
20	VCC	O	Internal LDO output. Connect a 1uF capacitor with it.
21	BT	O	Bootstrap pin. Connect a 100nF ceramic capacitor between BT pin and SW pin to provide bias voltage for internal driver circuit.
22, 23	PGND	O	power ground.
25	AGND	I/O	Exposed thermal pad. Connected with power ground through vias.

7 Specification

7.1 Absolute Maximum Rating

Over operating free-air temperature range (unless otherwise noted)⁽¹⁾

		Min.	Max.	Unit
Voltage ⁽²⁾	AVCC, ACP, ACN, ACDRV, CMSRC, STAT	-0.3	30	V
	SRP, SRN, PMID, CELL, /BATDRV	-0.3	25	V
	BT	-0.3	31	V
	SW	-2(10ns)	25	V
	VCC, VREF	-0.3	6.5	V
	OVPSET, NTC, TTC, ISET, ACSET	-0.3	6.5	V
T _J	Operating junction temperature	-40	155	°C
T _{stg}	Storage temperature	-65	155	°C

(1) Stresses beyond those listed under absolute maximum ratings may cause permanent damage to the device.

(2) All voltages are with respect to network ground terminal.

7.2 Thermal Information

THERMAL RESISTANCE ⁽¹⁾		QFN (3.5mmX5.5mm)	Unit
θ _{JA}	Junction to ambient thermal resistance	36	°C/W
θ _{JC}	Junction to case resistance	7	°C/W

(1) Measured on JESD51-7, 4-layer PCB.

7.3 ESD Ratings

		Min.	Max.	Unit
V _{ESD} ⁽¹⁾	Human-body Model (HBM) ⁽²⁾ All pins	-2	2	kV
	Charged-device Model (CDM) ⁽³⁾	500	500	V

(1) Electrostatic discharge (ESD) to measure device sensitivity and immunity to damage caused by assembly line electrostatic discharges into the device.

(2) Level listed above is the passing level per ANSI, ESDA, and JEDEC JS-001. JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.

(3) Level listed above is the passing level per EIA-JEDEC JESD22-C101. JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

7.4 Recommended Operation Conditions

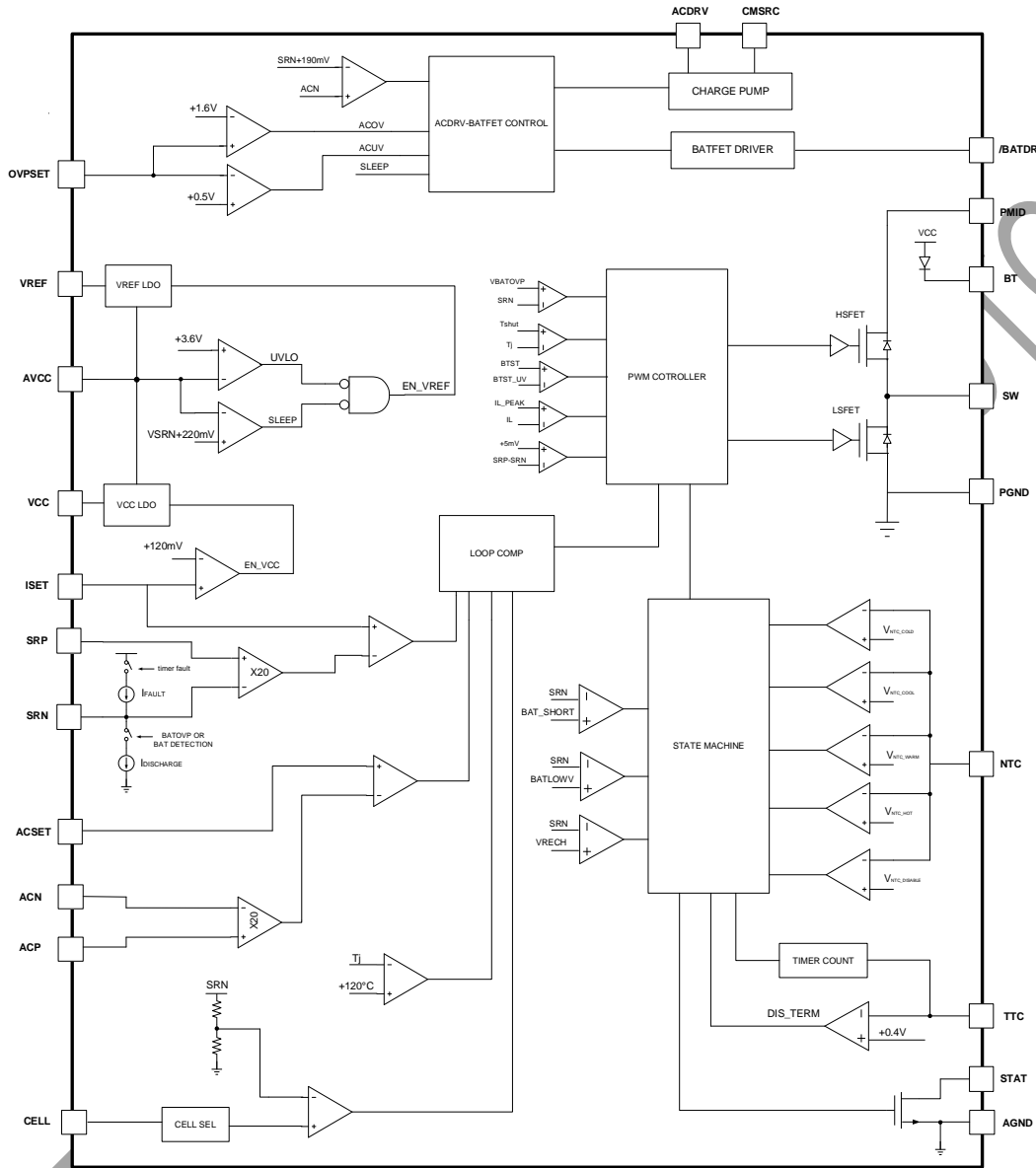
		MIN	TYP	MAX	UNIT
V _{BUS}	VBUS voltage range	4.2		24	V
V _{PMID}	PMID voltage range			24	V



V _{BAT}	VBAT voltage range			17.6	V
L	Inductance	2.2	3.3		μH
RS1	Input current sense resistor	5	10		mΩ
RS2	Charging current sense resistor	5	10		mΩ
T _A	Operating ambient temperature	-40		85	°C
T _J	Operating junction temperature	-40		125	°C

SOUTHCHIP SEMICONDUCTOR

8 Function Block Diagram





9 Electrical Characteristics

4.5V ≤ (PVCC, AVCC) ≤ 24V, -40°C < T_J < +125°C, typical values are at T_A = 25°C, T_A = 25°C unless otherwise noted.

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT	
SUPPLY VOLTAGE						
V _{AVCC_UVLO}	input under-voltage lockout threshold	Rising edge	3.5	3.8	4.1	V
		Hysteresis		400		mV
I _{Q_AVCC}	Quiescent current into AVCC pin	V _{AVCC} > V _{UVLO} , V _{AVCC} > V _{SRN} , V _{ISET} < 40mV, V _{BAT} = 12.6V, charger disabled		45	100	μA
		V _{AVCC} > V _{UVLO} , V _{AVCC} > V _{SRN} , V _{ISET} > 120mV, charger enabled, no switching			2	mA
		V _{AVCC} > V _{UVLO} , V _{AVCC} > V _{SRN} , V _{ISET} > 120mV, charger enabled, switching		5		mA
I _{Q_VBAT}	Quiescent current into SRN	V _{AVCC} > V _{UVLO} , V _{SRN} > V _{AVCC} (sleep mode), V _{BAT} = 12.6V, 3cells			15	μA
		V _{AVCC} > V _{UVLO} , V _{AVCC} > V _{SRN} , V _{ISET} < 40mV, V _{BAT} = 12.6V, Charge disabled			15	μA
		V _{AVCC} > V _{UVLO} , V _{AVCC} > V _{SRN} , V _{ISET} > 120mV, V _{BAT} = 12.6V, 3cells, charge termination		17	25	μA
POWERPATH						
V _{SLEEP}	Sleep mode threshold	V _{AVCC} - V _{SRN} falling	60	160	260	V
		Hysteresis		60		mV
V _{ACN-SRN}	Threshold to turn on BATFET	V _{ACN} - V _{SRN} falling	90	190	310	mV
	Hysteresis threshold to turn off BATFET	V _{ACN} - V _{SRN} rising		280		mV
POWER STAGE						
R _{DSON_HS}	Rdson resistance of high side FET		22		mΩ	
R _{DSON_LS}	Rdson resistance of low side FET		35		mΩ	
F _{SW}	Switching frequency		1000		kHz	
VREF LDO						
V _{VREF}	V _{VREF} output voltage	V _{AVCC} > V _{AVCC_UVLO} , No load	3.2	3.3	3.4	V
I _{VREF}	V _{VREF} current limit	V _{REF} = 0 V, V _{AVCC} > V _{UVLO}		60	120	mA
VCC DRIVER						
V _{VCC}	V _{VCC} output voltage	V _{AVCC} = 12V, I _{VCC} = 1~70mA	4.85	5.0	5.15	V
I _{VCC}	V _{VCC} current limit	V _{VCC} = 0V, V _{AVCC} > 10V, I _{SET} > 120mV	100		200	mA
ACDRV DRIVER						
I _{ACFET}	ACDRV charge pump current limit	V _{ACDRV} - V _{CMSRC} = 2 V		60		μA
V _{ACFET}	Gate drive voltage on ACFET	V _{ACDRV} - V _{CMSRC} when V _{AVCC} > V _{UVLO}	4.35	4.5		V



BATFET DRIVER						
$R_{DS_BAT_OFF}$	BATFET turnoff resistance		50		k Ω	
$R_{DS_BAT_ON}$	BATFET turn-on resistance		16		k Ω	
V_{BATDRV}	BATFET drive voltage	$V_{BATDRV} = V_{ACN} - V_{BATDRV}$ when $V_{AVCC} > 9V$ and BATFET is on	6		V	
INPUT CURRENT LIMIT						
K_{IDPM}	input current limit factor	$R_{SENSE} = 10m\Omega$	5		A/V	
I_{BUS}	Input current accuracy	$V_{ACP} - V_{ACN} = 80mV$	-3	3	%	
		$V_{ACP} - V_{ACN} = 40mV$	-4	4	%	
		$V_{ACP} - V_{ACN} = 20mV$	-7	7	%	
		$V_{ACP} - V_{ACN} = 5mV$	-20	20	%	
		$V_{ACP} - V_{ACN} = 2.5mV$	-25	25	%	
CHARGER FUNCTION						
V_{CHG}	Charge disable threshold	ISET falling	40	50	mV	
	Charge enable threshold	ISET rising	100	120	mV	
K_{ICHG}	Charge current limit factor	$R_{SENSE} = 10m\Omega$	5		A/V	
I_{CHG}	Charge constant current accuracy	$V_{SRP} - V_{SRN} = 40mV$	-5	5	%	
		$V_{SRP} - V_{SRN} = 20mV$	-5	5	%	
		$V_{SRP} - V_{SRN} = 5mV$	-25	25	%	
I_{ISET_LEAK}	Leakage current into ISET pin			100	nA	
K_{ITRK}	Trickle charging current ratio, respect to I_{CHG}		10%			
I_{TRK}	Trickle charging current accuracy	$V_{SRP} - V_{SRN} = 4mV$	-20	35	%	
		$V_{SRP} - V_{SRN} = 2mV$	-35	55	%	
K_{ITERM}	Termination charging current ratio, respect to I_{CHG}		10%			
I_{TERM}	Termination charging current accuracy	$V_{SRP} - V_{SRN} = 4mV$	-25	25	%	
		$V_{SRP} - V_{SRN} = 2mV$	-40	40	%	
V_{BAT_TRGT}	VBAT target voltage	CELL = GND	4.179	4.2	4.221	V
		CELL = Float	8.358	8.4	8.442	V
		CELL = High	12.537	12.6	12.663	V
V_{BAT_RECH}	Recharge threshold over VBAT target voltage	CELL = GND	70	100	130	mV
		CELL = Float	140	200	260	mV
		CELL = High	210	300	390	mV
t_{RECH_dgl}	Recharge deglitch time		10		ms	
V_{BAT_TRK}	Trickle charge threshold, measure on SRN	CELL = GND, rising	2.94	3	3.06	V
		CELL = Float, rising	5.88	6	6.12	V
		CELL = High, rising	8.82	9	9.18	V
		CELL = GND, falling hysteresis		200		mV



		CELL = Float, falling hysteresis	400		mV	
		CELL = High, falling hysteresis	600		mV	
t_{TRK_CC}	Trickle charge to CC charge deglitch		25		ms	
V_{BAT_SHORT}	Battery short threshold	Falling, CELL = GND	2		V	
		Falling, CELL = Float	4		V	
		Falling, CELL = High	6		V	
		Rising hysteresis, CELL = GND	200		mV	
		Rising hysteresis, CELL = Float	400		mV	
		Rising hysteresis, CELL = High	600		mV	
I_{SHORT}	Battery short charge current	$V_{BAT} < V_{BAT_SHORT}$	100		mA	
Safety timer						
K_{Timer_TRK}	Trickle charge timer factor		0.3		min/nF	
t_{TRK}	Trickle charge timer	$C_{TTC}=100nF$	30		min	
K_{timer_CC}	Constant charge timer factor		6		min/nF	
t_{CC}	Constant charge timer	$C_{TTC}=100nF$	10		H	
V_{TTC_LOW}	TTC pin low threshold			0.4	V	
I_{TTC}	TTC source/sink current		5		μA	
Battery Detection						
t_{WAKE}	Wake timer	Max time charge is enabled	500		ms	
I_{WAKE}	Wake current	$RS2 = 10m\Omega$	50	125	200	mA
$t_{Discharge}$	Discharge timer	Max time discharge current is applied	1		s	
$I_{Discharge}$	Discharge current		10		mA	
I_{FAULT}	Charge current after a time-out fault		2		mA	
V_{Wake}	Wake threshold to trigger battery detection, respect to V_{BAT_TARGET}	Measure on SRN	100		mV/Cell	
V_{DISCH}	Discharge threshold to detect battery absent	Measure on SRN	3		V/Cell	
Protection						
V_{ACOV}	Overvoltage rising threshold to turn off ACFET	OVPSET rising	1.57	1.6	1.63	V
		Falling hysteresis		50		mV
t_{ACOV_dgl}	Overvoltage rising deglitch	Rising edge		120		ns
		Falling edge		30		ms
V_{ACUV}	Undervoltage falling threshold to turn off ACFET	OVPSET falling	0.45	0.5	0.55	V
		Rising hysteresis		100		mV
t_{ACOV_dgl}	Undervoltage falling deglitch	Falling edge		40		ns
		Rising edge		30		ms
I_{LIM_PK}	Peak current limit		9		A	



V _{BATOV} P	VBAT over voltage protection	Rising edge, over VBAT target	104	%
		Hysteresis, over VBAT target	2	%
I _{BATOV} _DSG	VBAT over voltage discharge current	VBAT=4.6V	3	mA
NTC				
V _{COLD}	NTC cold temp threshold, refer to V _{REF}	Rising	70.2 70.8 71.4	%
		Falling hysteresis	0.6	%
V _{COOL}	NTC cool temp threshold, refer to V _{REF}	Rising	68 68.6 69.2	%
		Falling hysteresis	0.6	%
V _{WARM}	NTC warm temp threshold, refer to V _{REF}	Falling	55.6 56.1 56.7	%
		Rising hysteresis	0.9	%
V _{HOT}	NTC hot temp threshold, refer to V _{REF}	Falling	47.5 48.1 48.7	%
		Rising hysteresis	0.9	%
V _{DISNTC}	Disable NTC threshold, refer to V _{REF}	Falling	5	%
t _{NTC_dgl}	NTC status deglitch time	for NTC enter hot and cold	64	ms
		quit hot or cold	4	ms
STAT				
STAT _{LO}	STAT output low saturation Voltage	Sink current = 5 mA	0.5	V
LOGIC				
V _{IL}	cell input low voltage threshold		0.5	V
V _{MID}	cell input mid voltage threshold		1.1 1.6	V
V _{IH}	cell input high voltage threshold		2.5	V
STARTUP				
t _{DELAY}	Input delay time		5	μs
t _{DEBOUNCE}	Input debounce time		1.5	s
THERMAL REGULATION AND SHUTDOWN				
T _{REG}	Thermal loop regulation temperature		120	°C
T _{SD}	Thermal shutdown temperature	Rising edge	150	°C
		Hysteresis	20	°C
t _{SD_dgl}	Thermal shutdown rising deglitch	Rising edge	100	μs
	Thermal shutdown falling deglitch	Hysteresis	10	ms



10 Feature Description

10.1 Power Up

SC89133 is powered up when AVCC is above V_{UVLO} threshold. AVCC is supplied by adapter or battery internally. IC will start charging cycle if IC exits sleep mode.

10.2 Sleep Mode

if V_{AVCC} is above V_{UVLO} but $V_{AVCC} < V_{SRN} + 90mV$, SC89133 enters sleep mode to minimize current drain from the battery. In sleep mode, V_{REF} is disabled and charger is disabled, the STAT pin goes to high impedance.

10.3 VREF LDO

SC89133 integrates a 3.3V VREF LDO to provide reference voltage for input current limit and charge current setting. When AVCC is above UVLO and IC is not into sleep mode, the VREF LDO is initiated.

10.4 VCC driver

SC89133 integrates 5V VCC LDO to provide power for switching MOSFET driver. VCC is initiated when $V_{ISET} > 120mV$ and AVCC is powered up.

SC89133 enters standby mode when $V_{ISET} < 120mV$, VCC is disabled, charger is disabled.

10.5 Power path management

System power is switched from adapter or battery automatically. During sleep mode such as only battery exists, the BATFET is turned on to provide power from battery.

When adapter plugs in, SC89133 exits sleep mode, BATFET switches off and ACFET is turned on to provide power path from adapter to system.

When adapter is removed or an OV adapter plug-in, ACFET is turned off, then BATFET is turned on to supply system from battery.

10.6 Charge management

The SC89133 provides charge management functions for 1-3 cell Li-ion battery. The typical charge profile is shown in Figure 3.

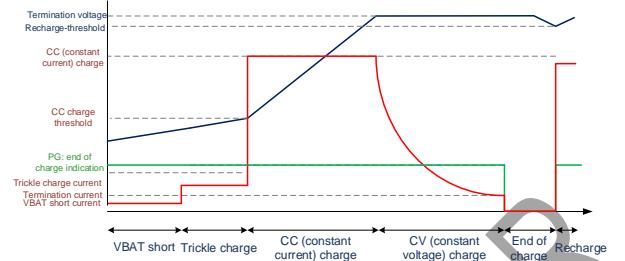


Figure 3. Typical charge profile

Charger cycle starts when following conditions is satisfied:

- (1) ISET pin above 120 mV.
- (2) Not in UVLO mode ($V_{AVCC} > V_{UVLO}$).
- (3) Not in SLEEP mode ($V_{AVCC} > V_{SRN}$).
- (4) Not in ACOV or ACUV mode. ($0.5V < V_{OVPSET} < 1.6V$)
- (5) 1.5s delay is complete after initial power up.
- (6) VCC LDO and VREF LDO voltages are at correct levels.
- (7) Thermal shut down is not valid.
- (8) NTC fault is not detected.
- (9) ACFET turns on
- (10) No safety timer is triggered

10.6.1 Battery Detection

When AVCC power on or VBAT falls down $< V_{BAT_RECH}$ (battery recharge voltage), IC initials a battery detection flow.

Step1: POR and VBAT < recharge voltage is triggered.

Step2: 8mA discharge current from SRN to GND and 1s timer starts. If $V_{BAT} > V_{BAT_TRK}$ and 1s timer expires, battery is present and IC start charging. Otherwise battery is absent, then go to next step.

Step3: 125mA charging current to VBAT and 500ms timer starts. If $V_{BAT} < V_{BAT_RECH}$ and lasting for 500ms, battery is present and IC start charging. Otherwise battery is absent, STAT pin is blinking, then repeat the battery detection cycle.

10.6.2 Trickle current Charge

When VBAT is lower than V_{BAT_TRK} (trickle charge threshold), the SC89133 charges the battery cells in trickle charge mode. In this mode, the charge current is regulated at 1/10 of the constant charge current programmed by ISET pin resistor.

If the 1/10 of the CC current is lower than 120mA, the trickle charge current will be clamped to 120mA. the trickle charge current is set as 10% of the fast charge rate set by ISET voltage.

$$I_{TRKLE} = \frac{V_{ISET}}{200 \times R_{SENSE}}$$



10.6.3 Constant Current (CC) Charge

When VBAT voltage is charged above V_{BAT_TRK} , the SC89133 enters into constant charge (CC) mode.

In this mode, the IC regulates VBAT sense current, and control the charging current decided by ISET pin. Use a voltage divider from VREF to ISET to AGND to set the fast charge current:

$$I_{CC} = \frac{V_{ISET}}{20 \times R_{SENSE}}$$

Where the RSENSE is the sense resistor between SRP and SRN.

The charger is disabled when ISET pin voltage is below 40 mV and enabled when ISET pin voltage is above 120 mV. ISET can be used as chip enable pin.

10.6.4 Constant Voltage (CV) Charge

The SC89133 operates in constant voltage (CV) mode after VBAT exceeds 98% of the termination voltage target VBAT_TRGT. In CV mode, the battery voltage is regulated at VBAT_TRGT. The charge current automatically drops until the battery is fully charged.

The battery target voltage can be configured through CELL pin voltage. Below table shows the relationship between the CELL setting and the VBAT target voltage.

Table 1 CELL pin to set VBAT target voltage

CELL pin	VBAT target voltage
High	12.6V
Float	8.4V
GND	4.2V

10.6.5 Charge Termination / End of Charge

When below conditions are valid, the SC89133 recognizes the battery cells are fully charged:

- 1) Termination voltage: the VBAT voltage is higher than 98% of VBAT_TRGT
- 2) Termination current: the charge current is less than termination current.

$$I_{TERM} = \frac{V_{ISET}}{200 \times R_{SENSE}}$$

Where the RSENSE is the sense resistor between SRP and SRN.

3) above two conditions are met together and with 500ms deglitch time

When batteries are fully charged, the SC89133 outputs floating at STAT pin, so the LED connected at STAT pin is off, indicating the end of charge (EOC). EOC is disabled when IC is in IINDPM or thermal regulation.

In EOC phase, the IC stops charging, ACFET is still turned on to provide power from adapter to system.

10.6.6 Recharge

After EOC, the SC89133 still monitors VBAT voltage. Once it detects the battery voltage falls below V_{VBAT_RECH} of VBAT_TRGT, it turns on charger and returns to CC mode with soft start again.

10.7 Charging Status Indication

When the SC89133 charges the battery in trickle charge/CC charge/CV charge mode, the STAT pin tied to GND internally, so the LED connected at STAT pin is turned on, indicating the charging is in process.

After the EOC conditions are met, the STAT pin outputs high impedance, indicating the battery cells are fully charged.

If the battery voltage drops below the recharge threshold V_{BAT_RECH} , the LED will be turned on again.

When fault happens, the STAT outputs high impedance and low at 0.5Hz frequency.

The charging status is as follow:

Table 2 STAT pin and working status

STAT status	IC working status
GND	Normal charging (VBAT short/ TC /CC /CV /Recharge)
High impedance	End of charging (EOC)/Sleep mode/ charger disable
0.5Hz blinking	Abnormal charging (ACOV/ACUV/ Safety timer triggered/ /NTC_HOT/ NTC_COLD /Tshut/battery Absent)

10.8 Input Current Limit

The SC89133 supports input current limit function. The input limit is set by voltage of IIN pin.

$$I_{BUS} = \frac{V_{ACSET}}{20 \times R_{SENSE}}$$

Where,

the RSENSE is the sense resistor between ACP and ACN.

IBUS is the input limit current.

V_{ACSET} is the voltage of ACSET pin, connected with resistor divider from VREF to AGND.

R_{SENSE} is the current sense resistor of input current of IBUS.

10.9 NTC

The SC89133 integrates JEITA standard NTC pin to support battery temperature protection function. Once SC89133 exits sleep mode, it keeps monitoring the battery cells' temperature through NTC pin and compares with V_{REF} voltage. When NTC faults (NTC hot or NTC cold) happens, the charger suspends, and the STAT starts blinking to alarm host. Only when NTC fault disappears, SC89133 resume charging after 40ms deglitch.

Below shows the NTC operation summary. NTC function can be also disabled through shorting the pin to ground.

Table 3 NTC operation

V _{NTC}	Operation
V _{NTC} > V _{COLD}	Stop charging
V _{COLD} > V _{NTC} > V _{COOL}	0.5*Charging Current
V _{COOL} > V _{NTC} > V _{WARM}	Normal charging
V _{WARM} > V _{NTC} > V _{HOT}	Constant Voltage -100mV
V _{HOT} > V _{NTC} > V _{DISNTC}	Stop charging
V _{DISNTC} > V _{NTC} >= 0	Disable NTC

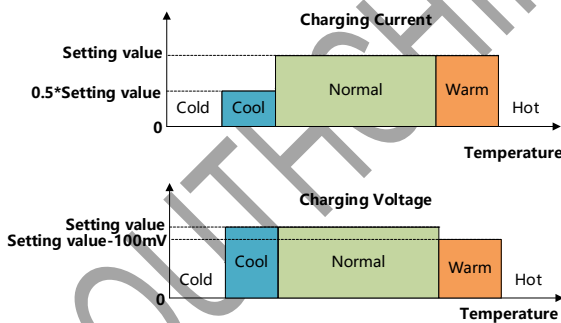


Figure 4. NTC Operation

SC89133 supports JEITA standard, IC monitors the voltage of NTC pin to check the temperature of battery. when IC detects the battery is in Cool State, it will decrease the constant charge current to be half of original value. Meanwhile, when IC detects the battery is in Warm State, the constant voltage decrease 100mV lower than setting

battery charging voltage.

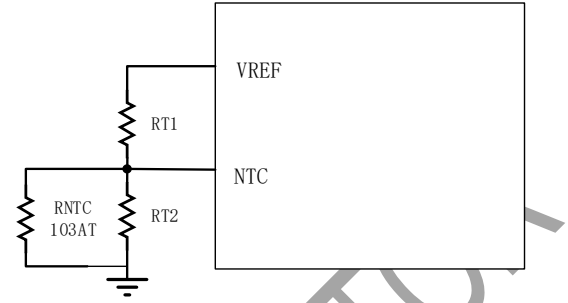


Figure 5. NTC Circuit

Use below equations to calculate the RT1/RT2 resistance when a 103AT NTC thermistor is used as shown in Figure 5.

$$R_{T2} = \frac{R_{COLD} \times R_{HOT} \times \left(\frac{1}{V_{COLD}} - \frac{1}{V_{HOT}} \right)}{R_{HOT} \times \left(\frac{1}{V_{HOT}} - 1 \right) - R_{COLD} \times \left(\frac{1}{V_{COLD}} - 1 \right)}$$

$$R_{T1} = \frac{V_{COLD}}{\frac{1}{R_{T2}} + \frac{1}{R_{COLD}}}$$

Where, R_{HOT} is the NTC resistance at the hot temperature threshold, R_{COLD} is the resistance at the cold threshold.

For example, set 0 °C(cold) to 60 °C (hot) to be the charging range. So R_{COLD} = 28.71 KΩ, R_{HOT} = 2.99 KΩ (resistance of 103AT thermistor at 0°C and 60°C)

So the calculation results are:

$$R_{T1} = 2.22 \text{ K}\Omega, R_{T2} = 6.64 \text{ K}\Omega;$$

With above setting, the cool temperature and warm temperature are 10 °C and 45 °C.

10.10 Input Undervoltage Lockout

When AVCC voltage is above V_{UVLO} voltage, the IC is enabled to allow proper operation. If AVCC falls below UVLO voltage, the IC is disabled.

10.11 Input Over and Under Voltage Protection

The SC89133 supports input over and under voltage protection. Once the IC detects the OVPSET pin voltage is above 1.6V or is below 0.5V, it enters into over voltage protection or under voltage protection. SC89133 will stop



switching instantly, ACFET is turned off to avoid abnormal adapter plug-in and BATFET is turned on to supply system from battery. At the same time, STAT pin blinks at 0.5Hz to indicate fault.

10.12 VBAT Over Voltage Protection

The SC89133 monitors VBAT voltage during the operation. Once it detects the VBAT is higher than 104% of the target voltage, over voltage protection is triggered and the IC stops switching at once, A 6mA discharging current path from SRP/SRN to AGND. The high-side FET is not turned on until the battery voltage goes below 102%. If battery overvoltage condition lasts for more than 30ms, charger is disabled.

10.13 VBAT Short Circuit Protection

Once the IC detects the VBAT voltage drops below V_{BAT_SHORT} , the VBAT short circuit protection is triggered. The IC regulates the short current to about 100mA.

After the short circuit fault is removed, the VBAT voltage is charged up. When VBAT voltage is higher than the short circuit threshold, the IC returns to normal operation.

10.14 Charging Over current Protection

The SC89133 monitor the peak inductor current cycle by cycle, it will clamp the peak inductor current to be about 9A.

10.15 Charging Under current Protection

When SRP-SRN voltage decreases below 5mV, the low-side FET is turned off for the rest of the switching cycle. IC Working in DCM mode. During discontinuous conduction mode, the low-side FET turns on for a short period of time when the bootstrap capacitor voltage drops below 4 V to provide refresh charge for the capacitor.

10.16 Safety Timer

SC89133 integrates internal timer to avoid over-time charging. safety timer in trickle charge phases is fixed 30 minutes. When SC89133 enters into constant current charge phase, safety timer is programmed by the capacitor connected between the TIM pin and AGND, and is given by the formula:

$$t = C_{TTC} \times K_{TTC}$$

Where,

$K_{TTC} = 6\text{min/nF}$ for fast charge phase (including CC and CV

phase), 0.3min/nF for trickle charge phase.

C_{TTC} is the capacitor connected to TTC pin.

For $C_{TTC} = 100\text{nF}$ typical application, the safety timer is 10 hours for fast charge phase. The safety timer is 30min for trickle charge phase.

TTC pin can be also used for mode selection function. Pull the TTC pin to AGND to disable both termination and fast charge safety timer. Pull the TTC pin to VREF to disable the safety timer but allow charge termination.

When the IC detects EOC condition, the IC clears the timer, and it does not restart the timer unless recharge phase starts, VBUS toggle happens or ISET pin toggles.

When IC enters VINREG, IDPM and thermal regulation, the timer related safety timer counting rate is slowed.

If the charging cycle does not end when the timer expires, SC89133 will transition to shutdown mode. The STAT starts blinking at 0.5Hz to indicate fault. SC89133 provides two Recovery ways to deal with timer fault according to battery voltage.

Condition 1: $V_{BAT} > V_{BAT_RECH}$ and safety timer is triggered.

Recovery Method: $V_{BAT} < V_{BAT_RECH}$ will clear the timer fault and battery detection will begin. A POR or taking ISET pin below 40 mV will also clear the fault.

Condition 2: $V_{BAT} < V_{BAT_RECH}$ and safety timer is triggered.

2mA charging current is used to detect a battery removal condition and remains on as long as the battery voltage stays below the recharge threshold. If battery is removed, $V_{BAT} > V_{BAT_RECH}$, 2mA charging current is disabled, and executes the recovery method in condition 1.

10.17 Thermal Regulation and Shutdown

In charging process, SC89133 keeps monitoring junction temperature. When IC detects $T_j > 120^\circ\text{C}$, it enters into thermal regulation loop and charging current is decreased gradually. If T_j still exceeds 120°C , charging current can be decreased to 0.

Once the SC89133 detects the junction temperature rises above 150°C , it shuts down the whole chip. When the temperature falls below 130°C , the chip is enabled again.

11 Application information

11.1 Input Filter Design

During adapter hot plug-in, the parasitic inductance and the input capacitor from the adapter cable form a second-order system. The voltage spike at the AVCC pin may be beyond the IC maximum voltage rating and damage the IC. The input filter must be carefully designed and tested to prevent an overvoltage event on the AVCC pin.

An electrolytic capacitor with high ESR as an input capacitor can damp the overvoltage spike well below the IC maximum pin voltage rating. Users must add this electrolytic capacitor (for example, 100uF) in the VBUS.

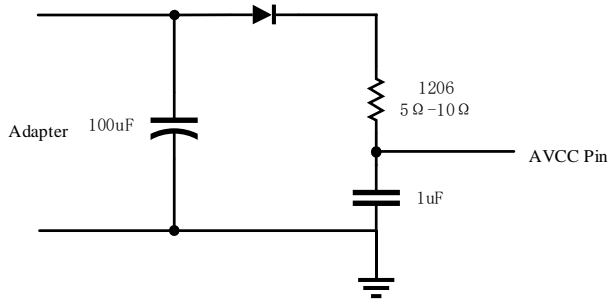


Figure 6. Input Filter

11.2 Input and Output Capacitor

The input current of the Buck converter is discontinuously, and the input capacitor should be carefully selected. The ripple current through input capacitor can be calculated as:

$$I_{RMS} = I_{CC} \sqrt{\frac{V_{BAT}}{V_{IN}} \left(1 - \frac{V_{BAT}}{V_{IN}}\right)}$$

where the I_{CC} is battery charging current, the V_{IN} is the input voltage (V_{BUS} or P_{MID}), V_{BAT} is the battery voltage. Since MLCC ceramic capacitor has good high frequency filtering and low ESR, X5R or X7R capacitors are recommended for input capacitors. Three 10uF input capacitors in PMID is enough for most applications.

The output voltage ripple of output capacitor can be calculated as:

$$V_{RIPPLE} = \frac{V_{BAT}}{f_{sw} \cdot L} \left(C_{ESR} + \frac{1}{8 \cdot f_{sw} \cdot C_{OUT}} \right) \left(1 - \frac{V_{BAT}}{V_{IN}} \right)$$

Where the f_{sw} is the switching frequency, C_{ESR} is the ESR of output capacitor. Also, X5R or X7R MLCC capacitors are recommended for output capacitors. 2x10uF output capacitors is enough for most applications.

MLCC capacitor of small package size normally has better high frequency filtering, so a 1 μ F MLCC of 0402 package size is highly recommended to added in parallel and put as close to VBUS and PMID pin as possible.

When selecting capacitors, the degrading effect of MLCC effective capacitance under DC bias must be considered. Ceramic capacitors can lose most capacitance at rated voltage. If the highest operating VBUS voltage is 12V, 25V voltage rating capacitor is recommended. Check the effective capacitance at the operating voltage to make sure the voltage ripple can be maintained.

11.3 Inductor Selection

2.2 μ H ~ 3.3 μ H inductor is recommended for loop stability.

The peak inductor current in charging mode can be calculated as

$$I_{L_{peak}} = I_{BAT} + \frac{V_{BAT} \cdot (V_{BUS} - V_{BAT})}{2 \cdot f_{sw} \cdot L \cdot V_{BUS} \cdot \eta}$$

where I_{BAT} is the battery charging current at VBAT side.

η is the power conversion efficiency. User can use 90% for calculation.

f_{sw} is the switching frequency

L is the inductor value

When selecting inductor, the inductor saturation current must be higher than the peak inductor current with enough margin (20% margin is recommended). The rating current of the inductor must be higher than the battery current.

The inductor DC resistance value (DCR) affects the conduction loss of switching regulator, so low DCR inductor is recommended especially for high power application. The conductor loss of inductor can be calculated roughly as

$$P_{L_DC} = I_L^2 \cdot DCR$$

I_L is the average value of inductor current, and it equals to IBAT.

Besides DC power loss, there are also inductor AC winding loss and inductor core loss, which are related to inductor peak current. Normally, higher peak current causes higher AC loss and core loss. The user shall consult with the inductor vendor to select the inductor which has small ESR at high frequency and small core loss.

11.4 Current Sense Resistor

10 m Ω should be used to sense IBAT current. Resistor of 1% or higher accuracy and low temperature coefficient is

recommended. The resistor power rating and temperature coefficient should be considered. The power dissipation can be roughly calculated as $P=I^2R$, and I is the RMS current flowing through the resistor. The resistor power rating should be higher than the calculated value.

Normally the resistor value is varied if the temperature increased and the variation is decided by temperature coefficient. If high accuracy of current limit is required, select lower temperature coefficient resistor as much as possible.

11.5 Layout Guide

1. The capacitors connected at VBUS/PMID/VBAT/VCC pins should be placed near the IC, and their ground connection to the ground pins should be as short as possible.
2. The current sense resistor should be close to the IC. The current sense traces should be connected to the current sense resistor's pads in Kelvin sense way as below, and routed in parallel (differential routing), and

the filter for current sense should be placed near the IC.

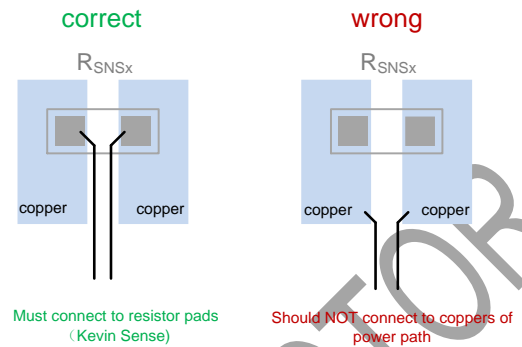
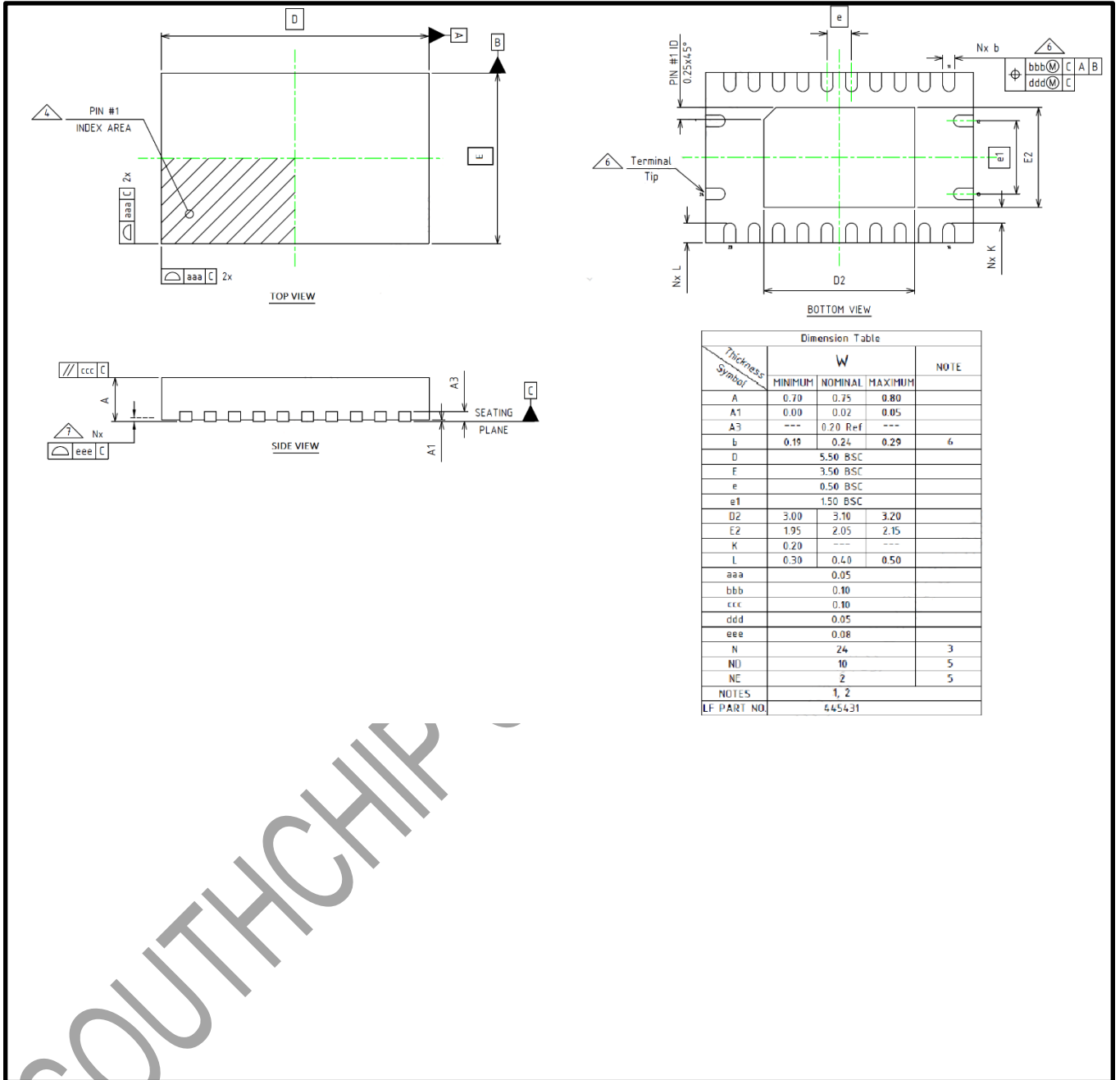


Figure 7. Current sense circuit

3. The AGND should be single connected to PGND close to IC.
4. The SW RC snubber circuit should be very close to IC SW and PGND pin.

MECHANICAL DATA

QFN (3.5mm x 5.5mm x 0.75mm)

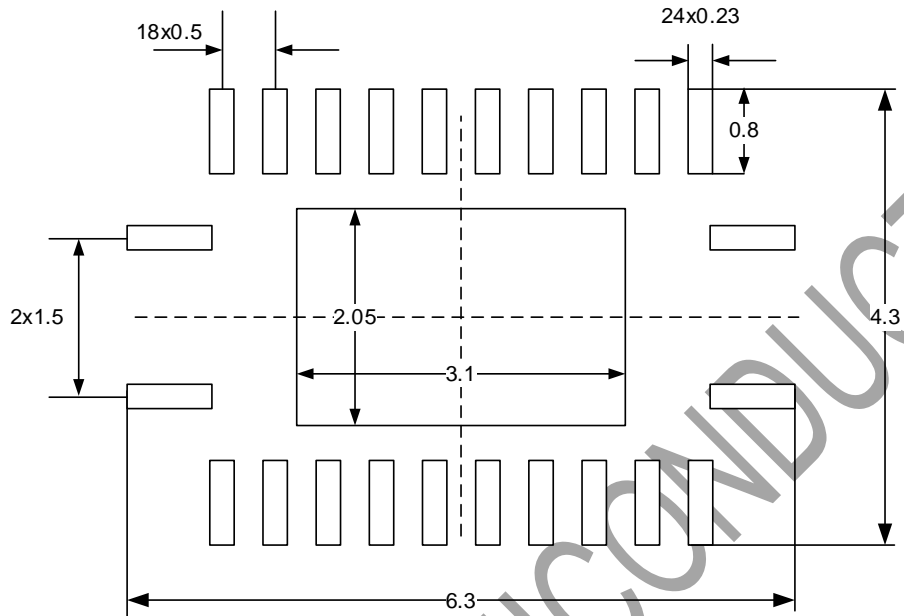


Thickness Symbol	W			NOTE
	MINIMUM	NOMINAL	MAXIMUM	
A	0.70	0.75	0.80	
A1	0.00	0.02	0.05	
A3	---	0.20 Ref	---	
b	0.19	0.24	0.29	6
D	5.50 BSC			
F	3.50 BSC			
e	0.50 BSC			
e1	1.50 BSC			
D2	3.00	3.10	3.20	
E2	1.95	2.05	2.15	
K	0.20	---	---	
L	0.30	0.40	0.50	
aaa	0.05			
bbb	0.10			
ccc	0.10			
ddd	0.05			
eee	0.08			
N	24			3
NO	10			5
NC	2			5
NOTES	1, 2			
LF PART NO.	445431			



RECOMMENDED FOOTPRINT

QFN-24 (3.5x5.5x0.75) (Unit: mm)



Note:

- A. All linear dimensions are in millimeters
- B. Publication IPC-7351 is recommended for alternate designs
- C. Customers should contact their board fabrication site for recommended solder mask tolerances and via tenting recommendations for vias placed in the thermal pad